

Product/Process Change Notification

N° 2020-129-B !! UPDATE !!

- Updated information marked in **BLUE TYPE**
- Original PCN N° 2020-129-A dated 2022-02-28

Dear customer,

please find attached an updated PCN for your attention:

Several changes affecting Classic HITFET™ 24V and Classic PROFET™ products with MSMART technology

If you have any questions, please do not hesitate to contact your local sales office.

Infineon Technologies AG

Postal address D-81726 München Internet www.infineon.com Headquarters Am Campeon 1-15, D-85579 Neubiberg Phone +49 (0)89 234-0

Chairman of the Supervisory Board Dr. Wolfgang Eder

Management Board Jochen Hanebeck (CEO), Constanze Hufenbecher, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg

Registered office Neubiberg Commercial register Amtsgericht München HRB 126492

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Products affected

Please refer to attached affected product list PCN_2020-129-B_[customer-no].pdf

Detailed change information

Subject: Several changes affecting Classic HITFET™ 24V and Classic PROFET™ products with MSMART technology

Reason/Motivation: Due to continuously raising demand for Infineon automotive products exceeding the capacity in location Villach, the wafer production and test for MSMART products is transferred to Kulim. As continuous improvement, mold compound is changed to halogen free for many MSMART products. For process harmonization, the top chip metallization of the affected Classic HITFET™ 24V products is changed to AlSiCu.

Description	Old	New
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip frontside)	Classic HITFET™ 24V products: Front side metallization of top chip AlSi	Classic HITFET™ 24V products: Front side metallization of top chip AlSiCu
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site	All products: Infineon Technologies Austria AG, Villach, Austria	All products: Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia
PROCESS - ASSEMBLY: Change of mold compound / encapsulation material	Classic HITFET™ 24V and Classic PROFET™ products in PG-TOx package: MP195H	Classic HITFET™ 24V and Classic PROFET™ products in PG-TOx package: KMC2110G
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site	All products: Infineon Technologies Austria AG, Villach, Austria	All products: Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia

Product identification

Wafer lot numbers from Villach start with VExxxxxx.
Wafer lot numbers from Kulim with 1Exxxxxx.
Traceability assured via date code.
SP ordering number changed for products with mold compound change.

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Anticipated impact of change

Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in form, fit and function expected.

DeQuMa-ID(s): SEM-PW-07 / SEM-PW-13 / SEM-PA-11 / SEM-TF-01

Attachments

PCN_2020-129-B_[customer-no].pdf	affected product list
3_cip20129_B	CIP update available upon request

Time schedule

	2020-129-A	2020-129-B
Final qualification report	available	update available
First samples available	on request	on request
Intended start of delivery [1]	2022-08-29	2022-08-29
Last order date (LOD) [2]	2022-08-29	2022-08-29
Last delivery date (LDD) [3]	2023-08-29	2023-08-29

[1] Provided date or earlier after customer approval.

[2] Last date where orders for unchanged products will be accepted.

[3] Last date for delivery of unchanged products. Delivery of changed products can be earlier (see Intended start of delivery) and depends on approval.

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